

# HVM14SR

# Silicon Epitaxial Planar PIN Diode for High Frequency Attenuator

REJ03G0114-0400Z (Previous: ADE-208-084C) Rev.4.00 Oct.08.2003

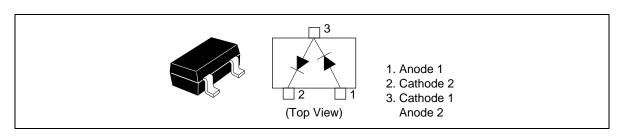
#### **Features**

- Low forward resistance. ( $r_f = 7.0 \Omega \text{ max}$ )
- Low capacitance. (C = 0.25 pF typ)
- MPAK package is suitable for high density surface mounting and high speed assembly.

### **Ordering Information**

Type No.	Laser Mark	Package Code
HVM14SR	H7	MPAK

#### **Pin Arrangement**



# **Absolute Maximum Ratings** \*1

 $(Ta = 25^{\circ}C)$ 

Item	Symbol	Value	Unit
Reverse voltage	$V_R$	50	V
Forward current	I <sub>F</sub>	50	mA
Power dissipation	Pd	100	mW
Junction temperature	Tj	125	°C
Storage temperature	Tstg	-55 to +125	°C

Note: 1. Absolute maximum ratings are described each unit separately.

## **Electrical Characteristics** \*1

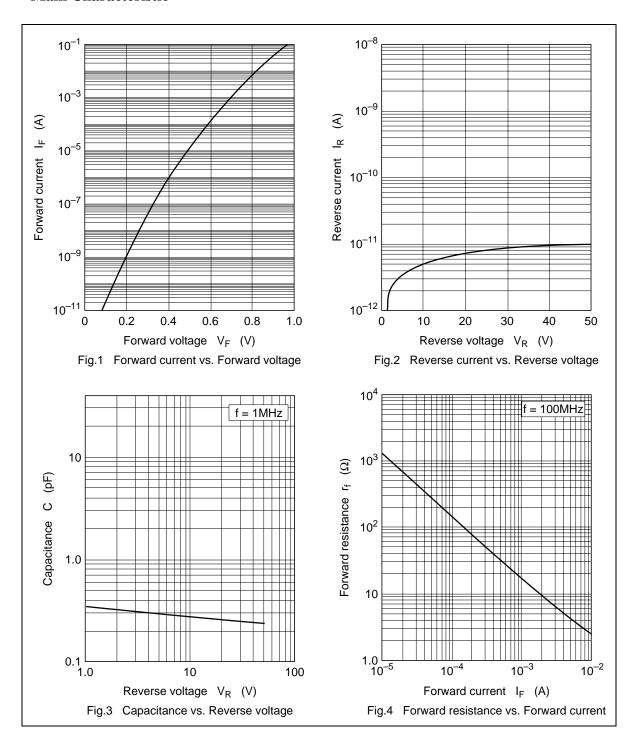
 $(Ta = 25^{\circ}C)$ 

Item	Symbol	Min	Тур	Max	Unit	Test Condition
Forward voltage	V <sub>F</sub>	_	_	1.0	V	I <sub>F</sub> = 50 mA
Reverse current	I <sub>R</sub>	_	_	100	nA	V <sub>R</sub> = 50 V
Capacitance	С	_	0.25	_	pF	V <sub>R</sub> = 50 V, f = 1 MHz
Forward resistance	r <sub>f</sub>	_	_	7.0	Ω	I <sub>F</sub> = 10 mA, f = 100 MHz
ESD-Capability *2	_	200	_	_	V	C = 200 pF, Both forward and reverse direction 1 pulse.

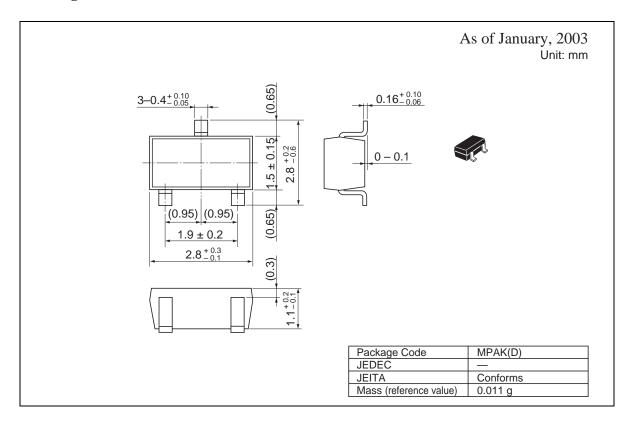
Notes: 1. Per one device.

2. Failure criterion;  $I_R \geq 200 \text{ nA}$  at  $V_R$  = 50 V

#### **Main Characteristic**



## **Package Dimensions**



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